

Amendments to the Claims:

Applicant has amended claims 1, 8 and 9, and added a new claim 21. Claims 13-20 are canceled.

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (currently amended): A package of a semiconductor device with a flexible wiring substrate, comprising:

a semiconductor substrate ~~with~~ having said semiconductor device and at least one pad on a surface thereof;

a plate located above said surface of said semiconductor substrate, said semiconductor device is covered by said plate, and said at least one pad is uncovered by said plate;

a bump bonded to said pad;

an adhesive layer on said bump; and

a said flexible wiring substrate having at least one contact section being electrically connected with said bump by said adhesive layer.

Claim 2 (original): The package of claim 1, wherein said bump is stud bump.

Claim 3 (original): The package of claim 2, wherein said bump is gold stud bump.

Claim 4 (original): The package of claim 1, wherein said adhesive layer includes non-conductive paste.

Claim 5 (original): The package of claim 2, wherein said adhesive layer includes non-conductive paste.

Claim 6 (original): The package of claim 1, wherein said adhesive layer includes anisotropic conductive paste.

Claim 7 (original): The package of claim 2, wherein said adhesive layer includes anisotropic conductive paste.

Claim 8 (currently amended): The package of claim 1, wherein said semiconductor ~~substrate~~ device comprises one or more having image sensors ~~on the surface thereof having said pad.~~

Claim 9 (currently amended): The package of claim 8, wherein said plate is a transparent plate ~~covered on the surface of said semiconductor substrate having~~ said image sensors.

Claim 10 (original): The package of claim 9, wherein said bump is stud bump.

Claim 11 (original): The package of claim 10, wherein said adhesive layer includes anisotropic conductive paste.

Claim 12 (original): The package of claim 10, wherein said adhesive layer includes non-conductive paste.

Claims 13-20 (Canceled)

Claim 21 (new): The package of claim 1, wherein said plate is held by an adhesive material and located above said semiconductor substrate.